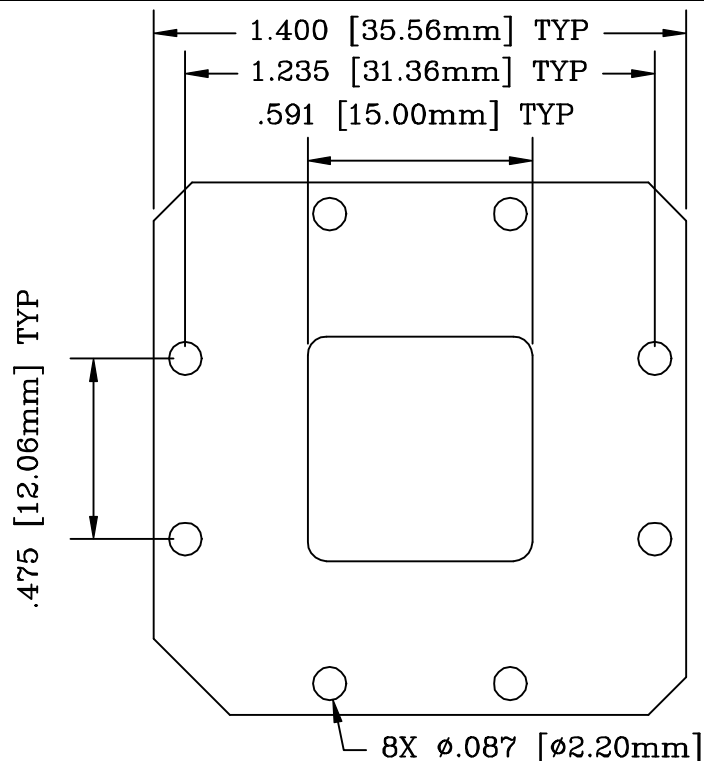


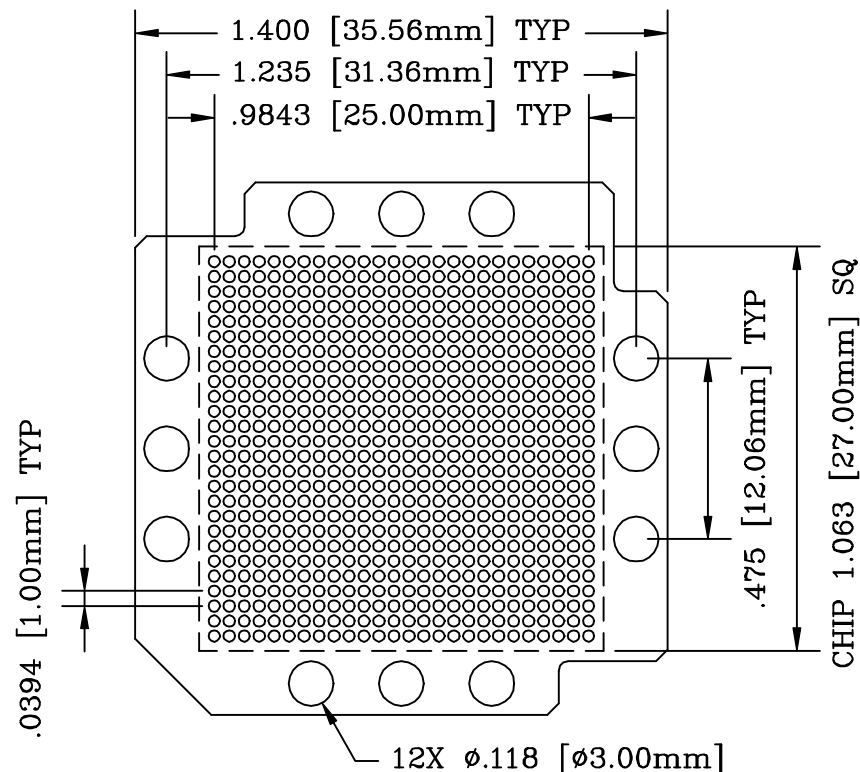
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	11/13/00	A.F.
B	UPDATED PAD LAYOUT	03/16/01	H.N.
C	UPDATED DRAWING & DIMS	10/10/01	H.N.
D	UPDATED REC. PAD LAYOUT	10/14/02	H.N.

SKT1201

DOD 41201



RETENTION FRAME



SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE		SOLDERTAIL = THRU HOLE STYLE	
REGULAR SMT STYLE XX = (-SM) YY = (-30)	RAISED SMT STYLE XX = (-RC) YY = (-29)	XX = (-ET) YY = (-70)	
 Pitch(PCB) * .0236 [Ø0.60mm] A PCB Layout		 Pitch(PCB) * .110 [2.80mm] .0197 [Ø0.50mm] PCB Layout	
BALL DIAMETER FOR: -30(SM) = .0197 [0.50mm] TO .0276 [0.70mm] -29(RC) = .0197 [0.50mm] TO .0276 [0.70mm]		PIN DIAMETER FOR: -70(ET) = .0114 [0.29mm]	
BALL HEIGHT FOR: -30(SM) = .0118 [0.30mm] TO .0197 [0.50mm] -29(RC) = .0118 [0.30mm] TO .0197 [0.50mm]		* All Dimensions Are Nominal For A .0394 [1.00mm] Pitch BGA Package	

PACKAGE SPECIFICATIONS

PIN COUNT	= 676
LEAD PITCH	= 1.00mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 27.00mm SQUARE

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.

— VLSI and SMT ADAPTERS and ACCESSORIES —

 2344 Walsh Avenue, Bldg.F
 Santa Clara, Ca 95051
 TEL:(408)982-0660
 FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 10/14/02	REVISION: D	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Hanh Nguyen	ITEM: S-MBG-26-676-XX	DESCRIPTION: BPW-676-3BG026-YY
Scale 1:2	DO NOT SCALE DRAWING		